

EUROPEAN DIRECTIVES

R.o.H.S. and W.E.E.E.

In order to meet the requirements of the R.o.H.S. and W.E.E.E directives issued by the European Union (2002/95/EC and 2002/96/EC), Microspire now removes the dangerous substances of its products.

As a consequence, Microspire upgraded its product lines:

- by using pure tin matte as external coating for termination (leadframes or pins): this plating is done on a Nickel intermediate layer. Microspire has chosen these materials in order to allow leaded and non leaded soldering processes, and minimize the possibility of tin whisker growth.
- by privileging solder alloys like SnAg or SnAgCu for the soldering operations: some Microspire products use high temperature melting solder (containing more than 85% lead). These solders are exempted from WEEE and RoHS regulations, due to the lack of viable compliant solder alloys. This high temperature solder is used only for internal product solder connections. External pin plating for these component types use the one above mentioned.

All our wound magnetics are RoHS by defect, the RoHS sign is indicated on the packaging of the products. For space market, the components are non RoHS by defect and RoHS upon request.

